



Product Change Notification / ALAN-22WDFU453

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**Date:**

13-Sep-2021

**Product Category:**

Switching Regulators

**PCN Type:**

Manufacturing Change

**Notification Subject:**

CCB 4386.002 Initial Notice: Qualification of Microchip Technology Tempe - Fab 2 (TMGR) as new fabrication site for Die#2 and Die#3 for selected MIC2851xx device families in 32L VQFN (6x6x0.9mm) package.

**Affected CPNs:**

[ALAN-22WDFU453\\_Affected\\_CPN\\_09132021.pdf](#)

[ALAN-22WDFU453\\_Affected\\_CPN\\_09132021.csv](#)

**Notification Text:**

**PCN Status:** Initial notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of Microchip Technology Tempe - Fab 2 (TMGR) as new fabrication site for Die#2 and Die#3 for selected MIC2851xx device families in 32L VQFN (6x6x0.9mm) package.

**Pre and Post Change Summary:**

	Pre Change	Post Change
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<b>Fabrication Location</b>	<b>Die # 1</b>	Microchip Technology Colorado (MCSO)	Microchip Technology Colorado (MCSO)
	<b>Die # 2</b>	MaxPower Semiconductor (MAPW)	Microchip Technology Tempe - Fab 2 (TMGR)
	<b>Die # 3</b>	MaxPower Semiconductor (MAPW)	Microchip Technology Tempe - Fab 2 (TMGR)
<b>Wafer Size</b>	<b>Die # 1</b>	6 inches	6 inches
	<b>Die # 2 and Die # 3</b>	8 inches	8 inches

**Impacts to Data Sheet:** None.

**Change Impact:**None.

**Reason for Change:**

To improve manufacturability and on-time delivery performance by qualifying TMGR as new fabrication site for Die#2 and Die#3.

**Change Implementation Status:**In Progress

**Estimated Qualification Completion Date:**July 2022

**Note:** Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

	<b>September 2021</b>						<b>July 2022</b>				
Workweek	36	37	38	39	40	->	26	27	28	29	30
Initial PCN Issue Date			X								
Qual Report Availability								X			
Final PCN Issue Date								X			

**Method to Identify Change:** Traceability code

**Qualification Plan:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:****September 13, 2021:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content

of the applicable products.

## **Attachments:**

[PCN\\_ALAN-22WDFU453\\_Qual Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## **Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

MIC28516T-E/PHA

MIC28516T-E/PHAVAO

MIC28517T-E/PHA

MIC28517T-E/PHAVAO



**MICROCHIP**

## **QUALIFICATION PLAN SUMMARY**

**PCN#: ALAN-22WDFU453**

**Date:  
September 6, 2021**

**Qualification of Microchip Technology Tempe - Fab 2 (TMGR)  
as new fabrication site for Die#2 and Die#3 for selected  
MIC2851xx device families in 32L VQFN (6x6x0.9mm)  
package.**



# MICROCHIP

**Purpose**

Qualification of Microchip Technology Tempe - Fab 2 (TMGR) as new fabrication site for Die#2 and Die#3 for selected MIC2851xx device families in 32L VQFN (6x6x0.9mm) package.

**CCB**

4386.002

Test	Sample Size	No. of Lots	Pass Criteria	Pre/Post Test Temp
Precondition	308	3	0/924	25 °C
High Temp Rev Bias (HTRB)	77	3	0/231	25 °C
High Temp Gate Bias (HTGB)	77	3	0/231	25 °C
Intermittent Op Life (IOL) * Required for automotive only	77	3	0/231	25 °C
Temp Cycle	77	3	0/231	25 °C
ESD HBM	30	1	Component classification is assigned based on passing pulse.	25 °C
ESD MM	30	1		25 °C
ESD CDM	30	1		25 °C